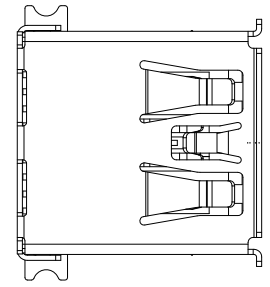
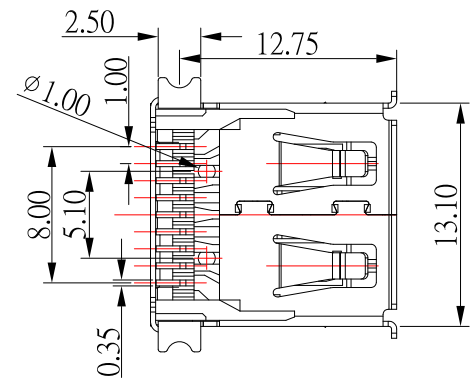


SUA-110M7B-30xHF-S277

鍍層厚度:

Blank	: 1u"
2	: 15u"
3	: 30u"



PCB EDGE
RECOMMENDED PCBA LAYOUT

NOTE:

- 1.MATERIAL:
 - 1.1 Housing: LCP
 - 1.2 Contact: Phosphor Bronze
 - 1.3 Shell: Brass
- 2.Finish:
 - 2.1 Contact: Plated Gold in Mating Area ;
Tin Plated on Solder Balls ;
Nickel under plated overall
 - 2.2 Shell: Nickel under Plated surface layer
- 3.SPECIFICATION:
 - 3.1 Current Rate: 1.5 A
 - 3.2 insulator Resistance:100MΩ Min
 - 3.3 Dielectric Strength: 100V AC
 - 3.4 Contact Resistance: 30mΩ Max
 - 3.5 Operation Temperature: -40°C ~ +85°C

Pin NUMBER	SIGNAL NAME
1	VBUS
2	D-
3	D+
4	GND
5	StdA_SSRX-
6	StdA_SSRX+
7	GND_DRAIN
8	StdA_SSTX-
9	StdA_SSTX+
Shell	Shield

CONTACT 建倚科技股份有限公司
CONTACT TECHNOLOGY CORP.

TOLERANCE UNLESS OTHERWISE STATED:
 Up to 5 ±0.2
 Above 5 ~ 15 ±0.3
 Above 15 ~ 30 ±0.4
 Above 30 ~ 50 ±0.5
 Angle ±0.3

3RD. ANGEL'S

UNITS MM

DRAWN BY:	DATE	MAT'L	TITLE	CONNECTOR
Jack Lu	04/11/23			
CHECKED BY:	DATE	FINISH	MODLE	USB 3.0 AF SMT本體長=14.45mm, 板上高7.0 有捲邊
Jacky Chen	04/11/23			
APPROVED BY:	DATE	SCALE	DWG NO.	SUA-110M7B-30xHF-S277
Tony Kao	04/11/23	1 : 1	PART NO.	SUA-110M7B-30xHF-S277
		SHEET NO.	1 of 1	SIZE A4
				VER R

ITEM NO.	DESCRIPTION	DRAWN	DATE